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### (54) MULTILAYER BAND-PASS FILTER

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(57)ABSTRACT

A band-pass filter includes a first inductor and a second inductor electromagnetically coupled to each other, a first ground terminal electrically connected to the first inductor, a second ground terminal electrically connected to the second inductor, and a stack for integrating the first inductor, the second inductor, the first ground terminal, and the second ground terminal. The first ground terminal and the second ground terminal are each connected to a ground and are not electrically connected to each other in the stack.

